

Title (en)
Method for producing a gallium phosphide epitaxial wafer.

Title (de)
Verfahren zur Herstellung eines epitaktischen Wafers.

Title (fr)
Méthode de fabrication d'une plaque epitaxiée.

Publication
EP 0654832 A1 19950524 (EN)

Application
EP 94307788 A 19941024

Priority
JP 29165693 A 19931122

Abstract (en)
A method for producing a GaP epitaxial wafer used for fabrication of light emitting diodes having higher brightness than light emitting diodes fabricated from a GaP epitaxial wafer produced by a conventional method. The method comprises the steps of: preparing a GaP layered substrate (15) with one or more GaP layers on a GaP single crystal substrate (10) in the first series of liquid phase epitaxial growth; obtaining a layered GaP substrate (15a) by eliminating surface irregularities of said GaP layered substrate (15) by mechano-chemical polishing to make the surface to be planar; and then forming a GaP light emitting layer composite (19) on said layered GaP substrate (15a) in the second series of liquid phase epitaxial growth. <IMAGE> <IMAGE>

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H01L 21/208 (2006.01); **H01L 21/304** (2006.01); **H01L 33/08** (2010.01); **H01L 33/12** (2010.01); **H01L 33/22** (2010.01); **H01L 33/30** (2010.01)

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Citation (search report)
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• [A] DATABASE WPI Week 8120, Derwent World Patents Index; AN 81-34495D
• [A] PATENT ABSTRACTS OF JAPAN vol. 13, no. 581 (E - 865) 21 December 1989 (1989-12-21)

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